

64 5. A circuit board for electronic parts, comprising:

a plate-like ground layer;

an insulating substrate disposed on said plate-like ground layer;

a plurality of leads disposed on the insulating substrate; and

a conductor disposed on an insulating material on said plurality of leads,

wherein said conductor disposed on said insulating material on said plurality of leads reduces a self inductance of said plurality of leads by flowing eddy current through said conductor, and

wherein said insulating substrate disposed on said plate-like ground layer reduces a self inductance of said plurality of leads by flowing eddy current through said plate-like ground layer.

6. The circuit board for electronic parts as claimed in claim 5, wherein said conductor forms a composite sheet together with said insulating material.

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**IN THE ABSTRACT OF THE DISCLOSURE:**

The Abstract of The Disclosure reads as follows:

65 A wiring board for a semiconductor device includes a wiring section disposed on an insulation board and an electromagnetic shielding film disposed at a position close to the wiring section. A distance defined between the wiring section and the electromagnetic shielding film is 150  $\mu\text{m}$  or less and a volume specific resistance of said electromagnetic shielding film is 30  $\mu\Omega\cdot\text{cm}$  or less at a room temperature. This structure reduces an inductance of the wiring section and inductive cross talk at frequencies